



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Features

- Package in 8mm tape on a 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Multi-color type.
- Pb-free.
- RoHS compliant version.



Descriptions

- The SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density and reduced storage space and finally smaller equipment to be obtained.
- Light weight makes them ideal for miniature applications.

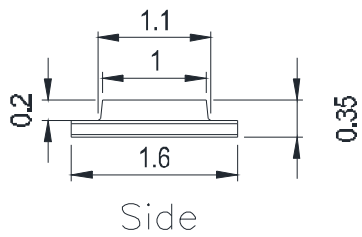
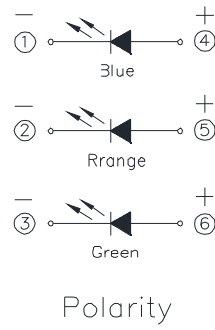
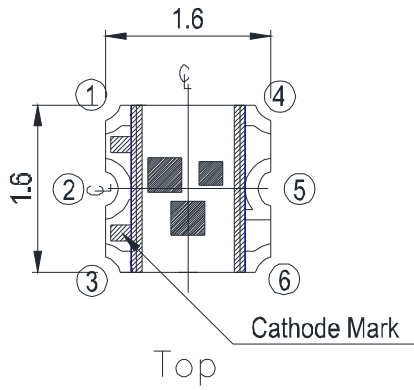
Applications

- Automotive.
- Portable equipment.
- General use.

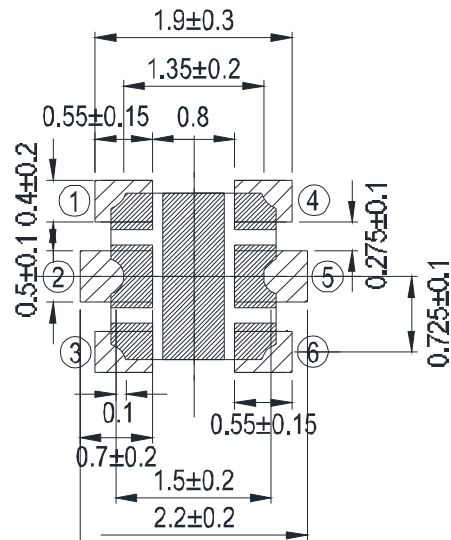
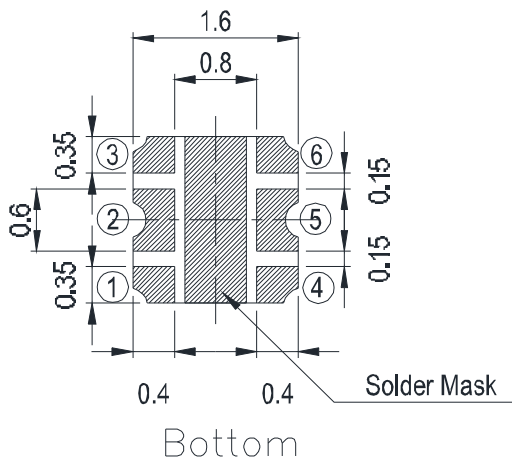
Device Selection Guide

| Chip | | | Lens Color |
|------|----------|-----------------|-------------|
| Type | Material | Emitted Color | |
| R | AlInGaN | Brilliant Red | Water Clear |
| G | InGaN | Brilliant Green | |
| B | InGaN | Blue | |

Package Outline Dimensions



Recommend soldering pad



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

Absolute Maximum Ratings (Ta=25°C)

| Parameter | Symbol | Rating | Unit |
|---|------------------|-----------------------------|------|
| Reverse Voltage | V _R | 5 | V |
| Forward Current | I _F | R6:25 GH:25 BH:25 | mA |
| Operating Temperature | T _{opr} | -40 ~ +85 | °C |
| Storage Temperature | T _{stg} | -40 ~ +90 | °C |
| Soldering Temperature | T _{sol} | 260 (for 5 seconds) | °C |
| Electrostatic Discharge | ESD | R6:2000 GH:150 BH:150 | V |
| Power Dissipation | P _d | R6:60 GH:110 BH:110 | mW |
| Peak Forward Current (Duty 1/10 @1KHz) | I _{FP} | R6:60 GH:100 BH:100 | mA |

Specific binning requirements- please contact our home office

Electro-Optical Characteristics (Ta=25°C)

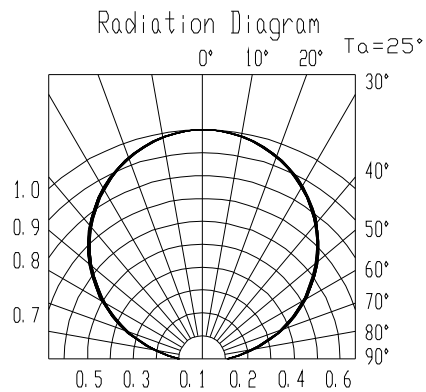
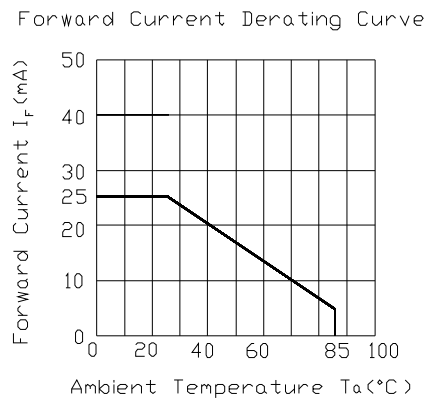
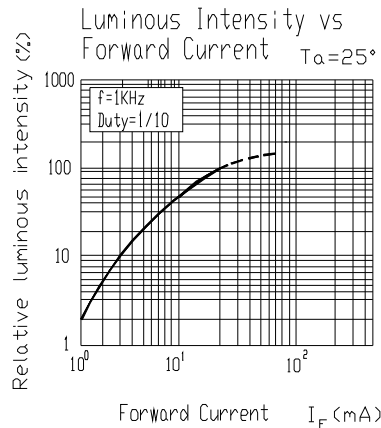
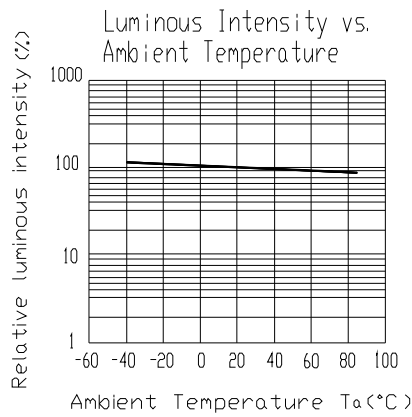
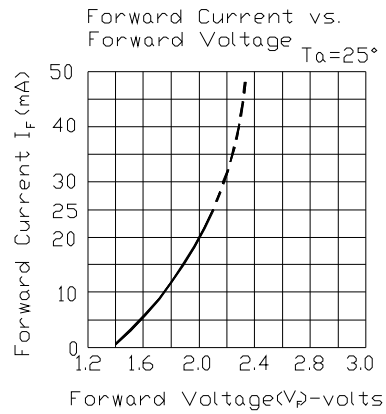
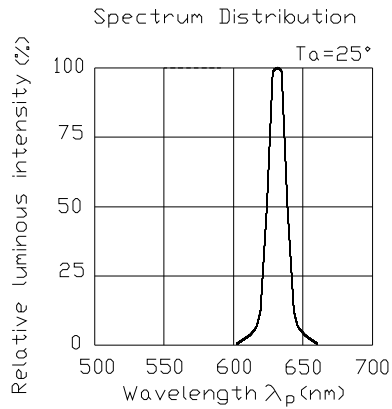
| Parameter | Symbol | Min. | Typ. | Max. | Unit | Condition |
|------------------------------|-------------------|-------|-------|-------|------|--------------------|
| Luminous Intensity | R6 | 72 | 100 | | mcd | IF=20mA |
| | Iv GH | 112 | 180 | ----- | | |
| | BH | 28.5 | 50 | | | |
| Viewing Angle | 2 θ 1/2 | ----- | 120 | ----- | deg | |
| Peak Wavelength | R6 | | 632 | | nm | |
| | λ p GH | ----- | 518 | ----- | | |
| | BH | | 468 | | | |
| Dominant Wavelength | R6 | | 624 | | nm | |
| | λ d GH | ----- | 525 | ----- | | |
| | BH | | 470 | | | |
| Spectrum Radiation Bandwidth | R6 | | 20 | | nm | |
| | Δ λ GH | ----- | 35 | ----- | | |
| | BH | | 35 | | | |
| Forward Voltage | R6 | | 2.0 | 2.4 | V | |
| | V _F GH | ----- | 3.3 | 3.9 | | |
| | BH | | 3.3 | 3.9 | | |
| Reverse Current | R6 | | | 10 | μ A | V _R =5V |
| | I _R GH | ----- | ----- | 50 | | |
| | BH | | | 50 | | |

Notes:

1. Tolerance of Luminous Intensity ± 10%
2. Tolerance of Dominant Wavelength ± 1nm
3. Tolerance of Forward Voltage ± 0.1V

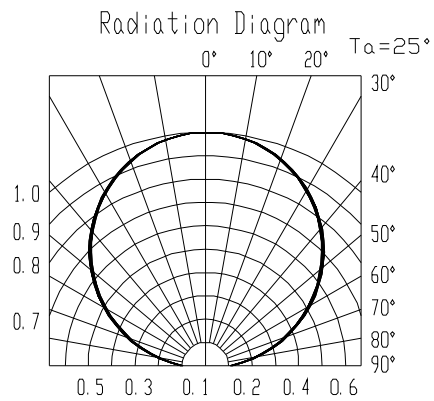
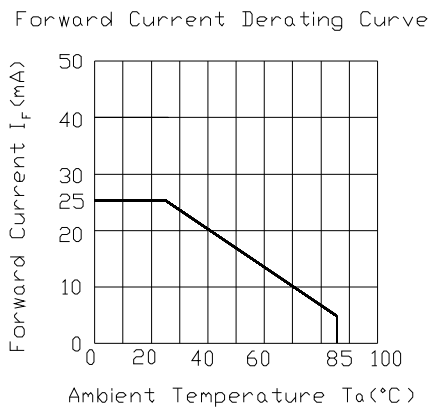
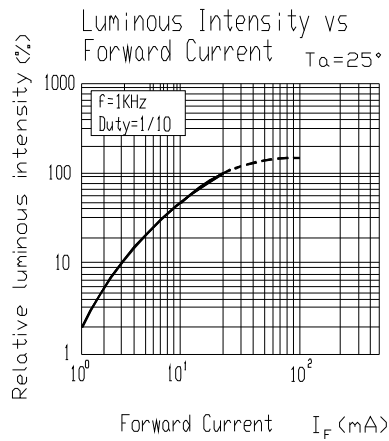
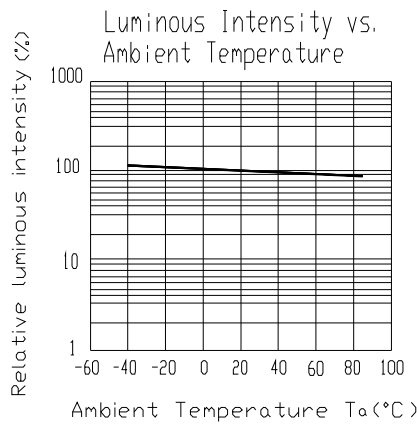
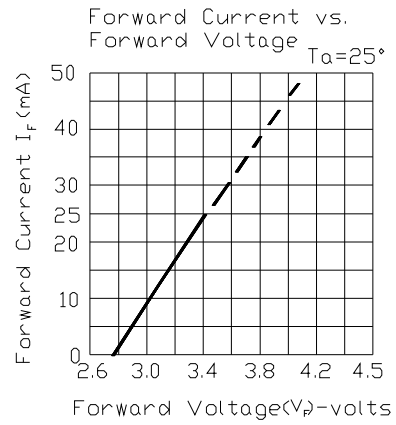
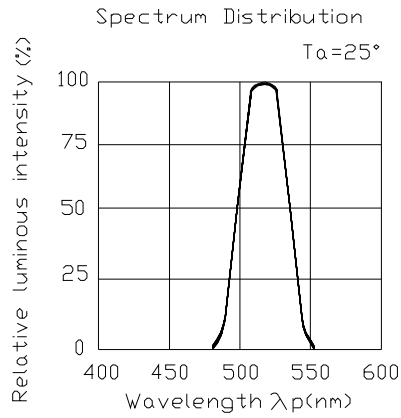
Typical Electro-Optical Characteristics Curves

R6



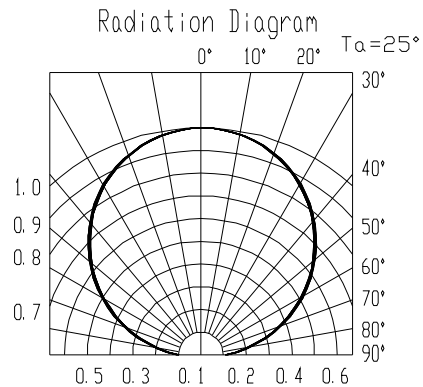
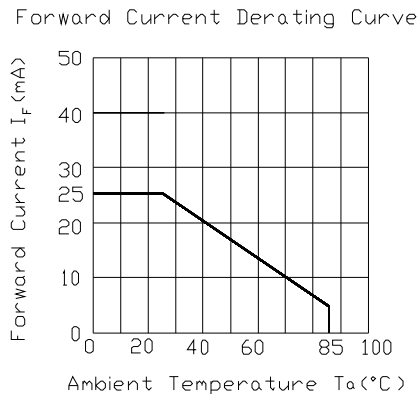
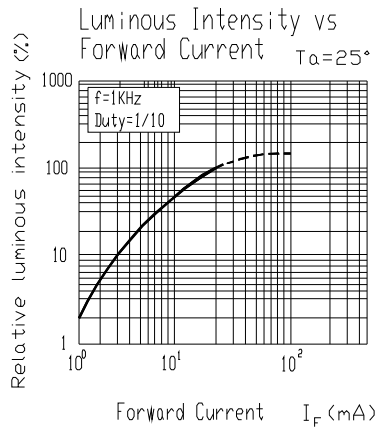
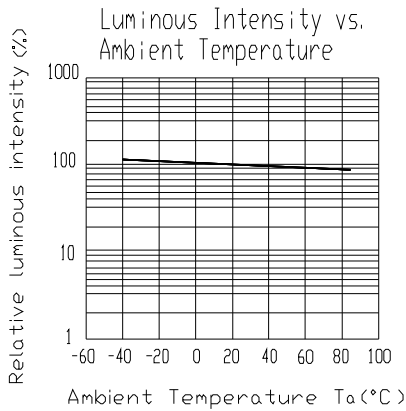
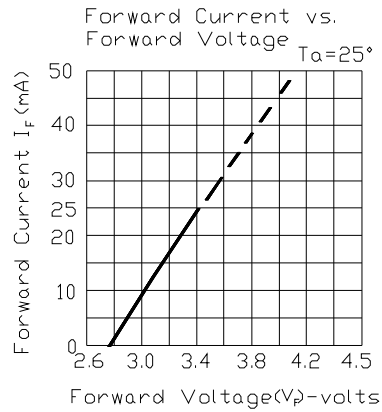
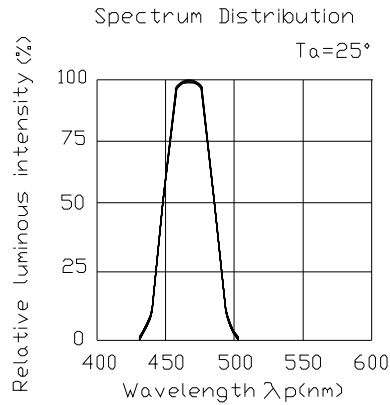
Typical Electro-Optical Characteristics Curves

GH

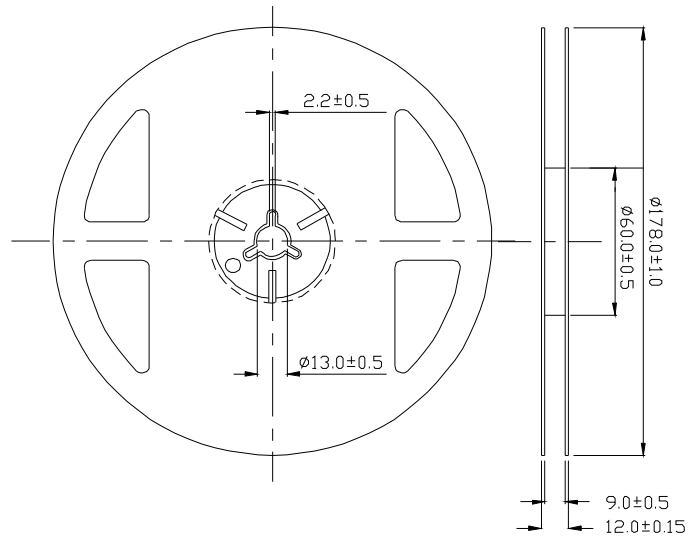


Typical Electro-Optical Characteristics Curves

BH

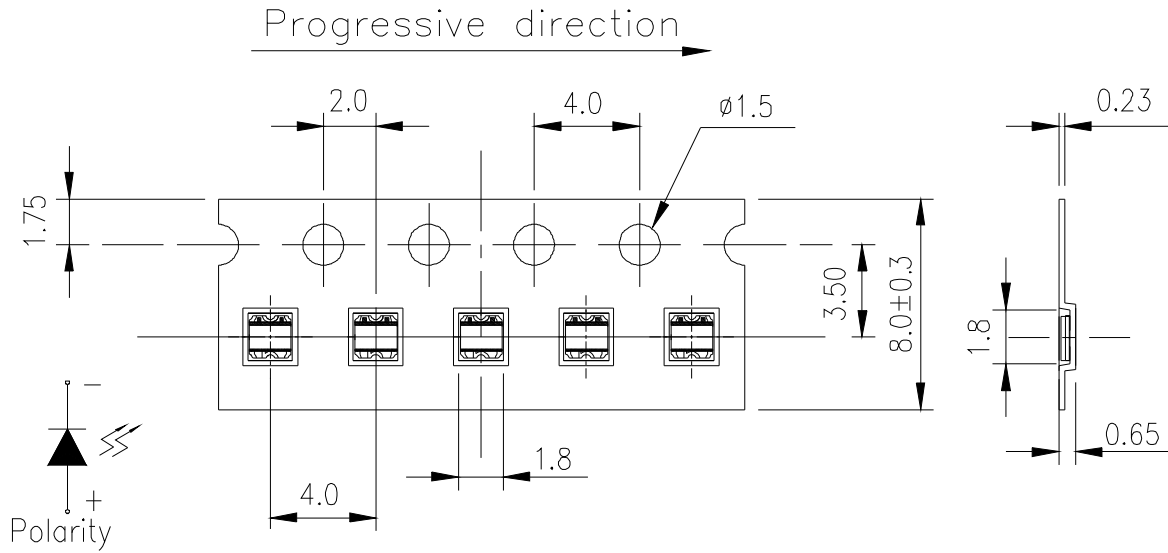


Reel Dimensions



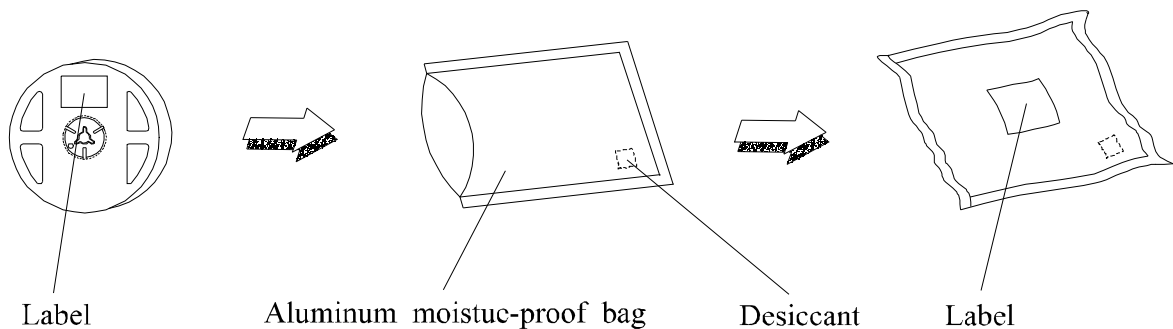
Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$,Unit = mm

Moisture Resistant Packaging



Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

| No. | Items | Test Condition | Test Hours/Cycles | Sample Size | Ac/Re |
|-----|----------------------------------|--|-------------------|-------------|-------|
| 1 | Reflow Soldering | Temp. : 260°C ±5°C 5sec. | 6 Min. | 22 PCS. | 0/1 |
| 2 | Temperature Cycle | H : +100°C 15min ∫ 5 min L : -40°C 15min | 300 Cycles | 22 PCS. | 0/1 |
| 3 | Thermal Shock | H : +100°C 5min ∫ 10 sec L : -10°C 5min | 300 Cycles | 22 PCS. | 0/1 |
| 4 | High Temperature Storage | Temp. : 100°C | 1000 Hrs. | 22 PCS. | 0/1 |
| 5 | Low Temperature Storage | Temp. : -40°C | 1000 Hrs. | 22 PCS. | 0/1 |
| 6 | DC Operating Life | IF = 20 mA | 1000 Hrs. | 22 PCS. | 0/1 |
| 7 | High Temperature / High Humidity | 85°C / 85% RH | 1000 Hrs. | 22 PCS. | 0/1 |

Precautions For Use

1. Customer must apply resistors for protection , otherwise slight a voltage shift will cause a big current change.

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less.

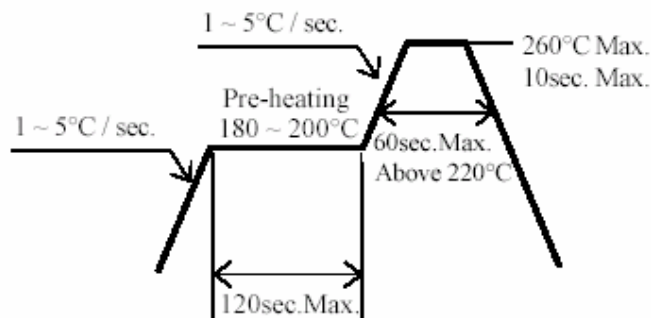
2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 280°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.